

# E4M0060075K1

Silicon Carbide Power MOSFET  
E-Series Automotive  
N-Channel Enhancement Mode



## Features

- Optimized package with separate driver source pin
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery ( $Q_{rr}$ )
- Halogen free, RoHS compliant
- Automotive Qualified (AEC-Q101) and PPAP Capable

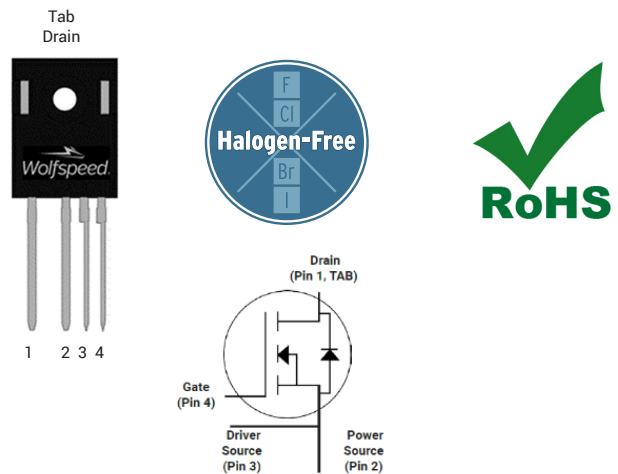
## Benefits

- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

## Applications

- Motor Control
- EV Battery Chargers
- High Voltage DC/DC Converters

## Package



Part Number	Package	Marking
E4M0060075K1	TO-247-4L	E4M0060075K1

## Maximum Ratings ( $T_c = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Value	Unit	Note	
$V_{DSmax}$	Drain - Source Voltage	750	V		
$V_{GSmax}$	Gate - Source Voltage	-8/+19	V	Note: 1	
$I_D$	Continuous Drain Current, $V_{GS} = 15\text{ V}$	$T_c = 25^\circ\text{C}$	35	A	Fig. 19 Note: 2
		$T_c = 100^\circ\text{C}$	26		
$I_{D(pulse)}$	Pulsed Drain Current, Pulse width $t_p$ limited by $T_{jmax}$	101	A	Fig. 22	
$P_D$	Power Dissipation, $T_c=25^\circ\text{C}$ , $T_j = 175^\circ\text{C}$	126	W	Fig. 20 Note: 2	
$T_J, T_{stg}$	Operating Junction and Storage Temperature	-55 to +175	$^\circ\text{C}$		
$T_L$	Solder Temperature, 1.6mm (0.063") from case for 10s	260	$^\circ\text{C}$		
$M_d$	Mounting Torque, M3 or 6-32 screw	1	Nm lbf-in		
		8.8			

Note (1): Recommended turn off / turn on gate voltage  $V_{GS} = -4V..0V / +15V$

Note (2): Verified by design

**Electrical Characteristics** ( $T_C = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	750			V	$V_{GS} = 0\text{ V}, I_D = 100\ \mu\text{A}$	
$V_{GS(th)}$	Gate Threshold Voltage	1.8	2.6	3.8	V	$V_{DS} = V_{GS}, I_D = 3.67\ \text{mA}$	Fig. 11
			2.1		V	$V_{DS} = V_{GS}, I_D = 3.67\ \text{mA}, T_J = 175^\circ\text{C}$	
$I_{DSS}$	Zero Gate Voltage Drain Current		1	50	$\mu\text{A}$	$V_{DS} = 750\ \text{V}, V_{GS} = 0\ \text{V}$	
$I_{GSS}$	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 15\ \text{V}, V_{DS} = 0\ \text{V}$	
$R_{DS(on)}$	Drain-Source On-State Resistance		60	78	m $\Omega$	$V_{GS} = 15\ \text{V}, I_D = 13.4\ \text{A}$	Fig. 4, 5, 6
			87			$V_{GS} = 15\ \text{V}, I_D = 13.4\ \text{A}, T_J = 175^\circ\text{C}$	
$g_{fs}$	Transconductance		10		S	$V_{DS} = 20\ \text{V}, I_{DS} = 13.4\ \text{A}$	Fig. 7
			8			$V_{DS} = 20\ \text{V}, I_{DS} = 13.4\ \text{A}, T_J = 175^\circ\text{C}$	
$C_{iss}$	Input Capacitance		1203		pF	$V_{GS} = 0\ \text{V}, V_{DS} = 0\ \text{V to } 500\ \text{V}$ $F = 100\ \text{kHz}$ $V_{AC} = 25\ \text{mV}$	Fig. 17, 18
$C_{oss}$	Output Capacitance		69				
$C_{rss}$	Reverse Transfer Capacitance		7				
$E_{oss}$	$C_{oss}$ Stored Energy		10		$\mu\text{J}$		Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		90		pF	$V_{GS} = 0\ \text{V}, V_{DS} = 0... 500\ \text{V}$	Note: 3
$C_{o(tr)}$	Effective Output Capacitance (Time Related)		129		pF		
$E_{ON}$	Turn-On Switching Energy (External Diode)		52		$\mu\text{J}$	$V_{DS} = 500\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}, I_D = 13.4\ \text{A},$ $R_{G(ext)} = 2.5\ \Omega, L = 135\ \mu\text{H}, T_J = 175^\circ\text{C}$ FWD = External SiC DIODE	Fig. 26, 28
$E_{OFF}$	Turn Off Switching Energy (External Diode)		16				
$E_{ON}$	Turn-On Switching Energy (Body Diode FWD)		56		$\mu\text{J}$	$V_{DS} = 500\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}, I_D = 13.4\ \text{A},$ $R_{G(ext)} = 2.5\ \Omega, L = 135\ \mu\text{H}, T_J = 175^\circ\text{C}$ FWD = Internal Body Diode	Fig. 26, 28
$E_{OFF}$	Turn-Off Switching Energy (Body Diode FWD)		16				
$t_{d(on)}$	Turn-On Delay Time		8		ns	$V_{DD} = 500\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}$ $I_D = 13.4\ \text{A}, R_{G(ext)} = 2.5\ \Omega, L = 135\ \mu\text{H}$ Timing relative to $V_{DS}$ Inductive load	Fig. 27, 28
$t_r$	Rise Time		9				
$t_{d(off)}$	Turn-Off Delay Time		16				
$t_f$	Fall Time		9				
$R_{G(int)}$	Internal Gate Resistance		3.0		$\Omega$	$f = 1\ \text{MHz}, V_{AC} = 25\ \text{mV}$	
$Q_{gs}$	Gate to Source Charge		14		nC	$V_{DS} = 500\ \text{V}, V_{GS} = -4\ \text{V}/15\ \text{V}$ $I_D = 13.4\ \text{A}$ Per IEC60747-8-4 pg 21	Fig. 12
$Q_{gd}$	Gate to Drain Charge		18				
$Q_g$	Total Gate Charge		52				

Note (3):  $C_{o(er)}$ , a lumped capacitance that gives same stored energy as  $C_{oss}$  while  $V_{ds}$  is rising from 0 to 500V

$C_{o(tr)}$ , a lumped capacitance that gives same charging time as  $C_{oss}$  while  $V_{ds}$  is rising from 0 to 500V


**Reverse Diode Characteristics** ( $T_c = 25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$V_{SD}$	Diode Forward Voltage	4.8		V	$V_{GS} = -4\text{ V}, I_{SD} = 6.7\text{ A}, T_J = 25^\circ\text{C}$	Fig. 8, 9, 10
		4.2		V	$V_{GS} = -4\text{ V}, I_{SD} = 6.7\text{ A}, T_J = 175^\circ\text{C}$	
$I_S$	Continuous Diode Forward Current		22	A	$V_{GS} = -4\text{ V}, T_c = 25^\circ\text{C}$	
$I_{S, pulse}$	Diode pulse Current		101	A	$V_{GS} = -4\text{ V}$ , pulse width $t_p$ limited by $T_{jmax}$	
$t_{rr}$	Reverse Recovery time	14		ns	$V_{GS} = -4\text{ V}, I_{SD} = 13.4\text{ A}, V_R = 500\text{ V}$ $dif/dt = 6160\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
$Q_{rr}$	Reverse Recovery Charge	327		nC		
$I_{rrm}$	Peak Reverse Recovery Current	40		A		
$t_{rr}$	Reverse Recovery time	23		ns	$V_{GS} = -4\text{ V}, I_{SD} = 13.4\text{ A}, V_R = 500\text{ V}$ $dif/dt = 2150\text{ A}/\mu\text{s}, T_J = 175^\circ\text{C}$	
$Q_{rr}$	Reverse Recovery Charge	220		nC		
$I_{rrm}$	Peak Reverse Recovery Current	18		A		

**Thermal Characteristics**

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.91	1.19	$^\circ\text{C}/\text{W}$		Fig. 21



Typical Performance

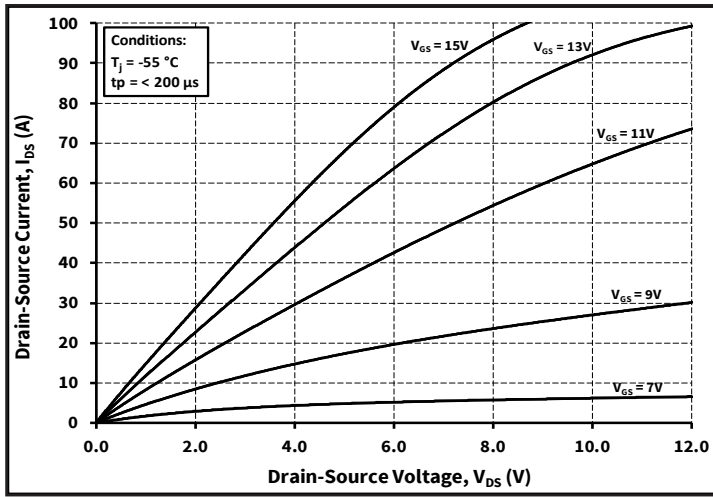


Figure 1. Output Characteristics  $T_J = -55\text{ }^\circ\text{C}$

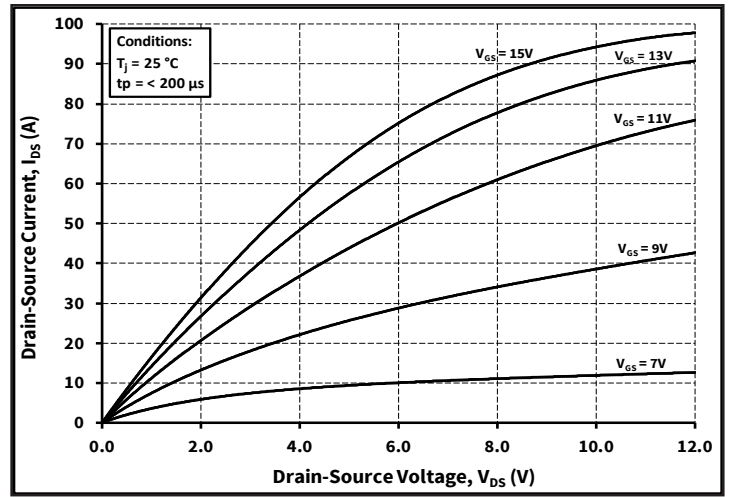


Figure 2. Output Characteristics  $T_J = 25\text{ }^\circ\text{C}$

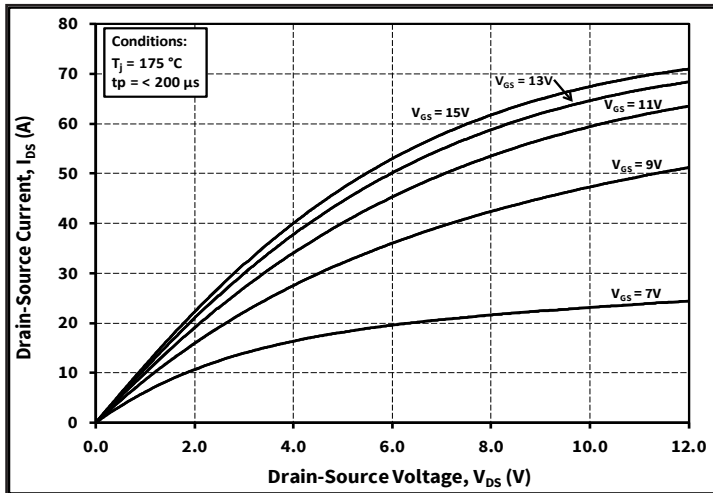


Figure 3. Output Characteristics  $T_J = 175\text{ }^\circ\text{C}$

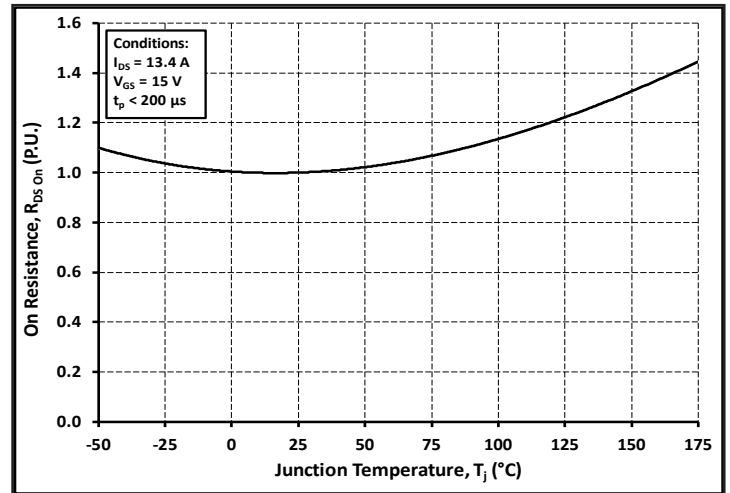


Figure 4. Normalized On-Resistance vs. Temperature

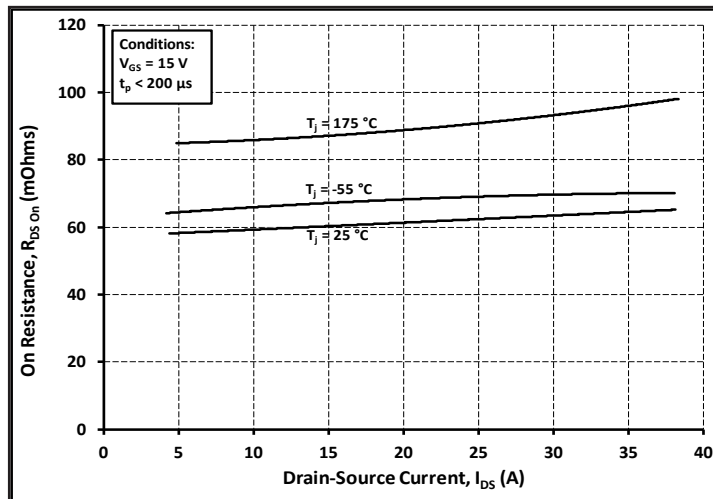


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

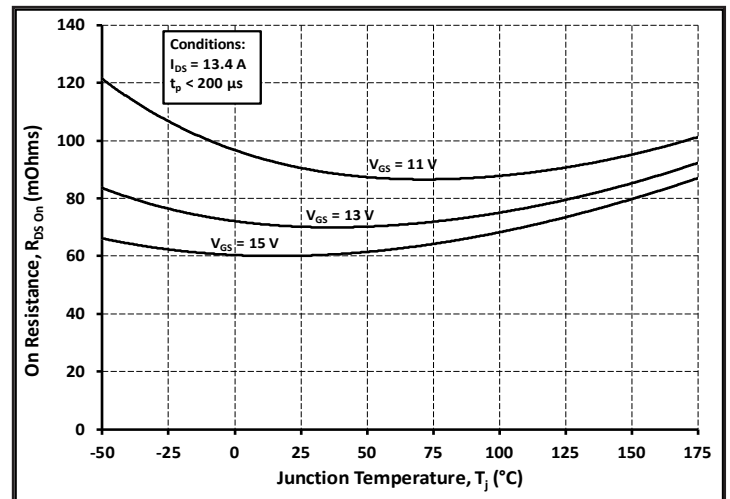


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage



Typical Performance

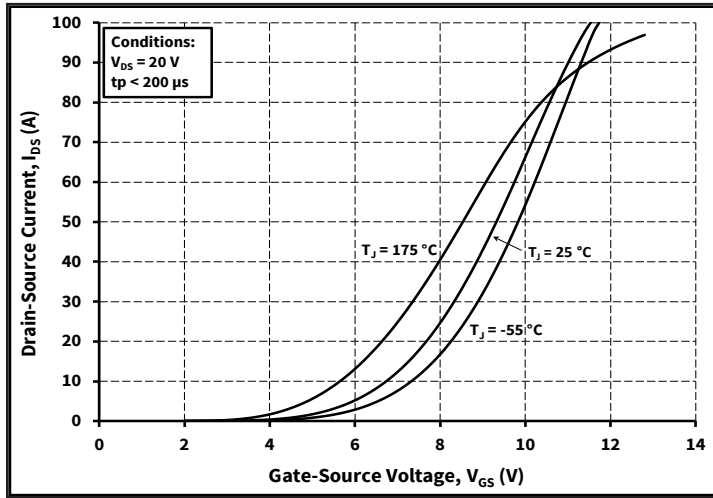


Figure 7. Transfer Characteristic for Various Junction Temperatures

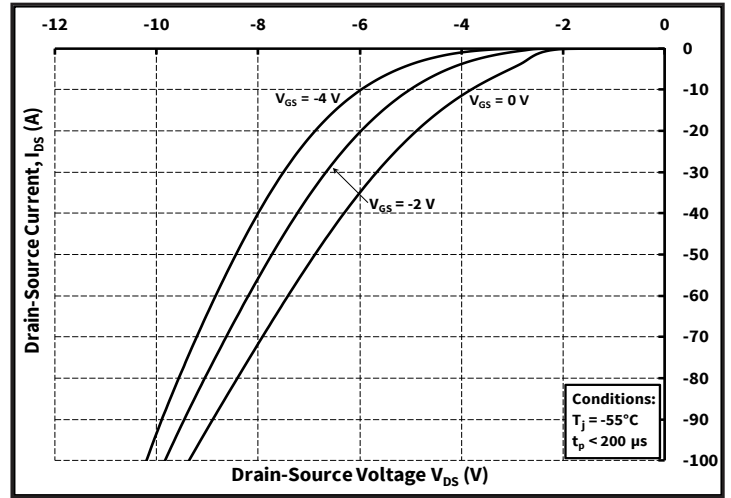


Figure 8. Body Diode Characteristic at -55 °C

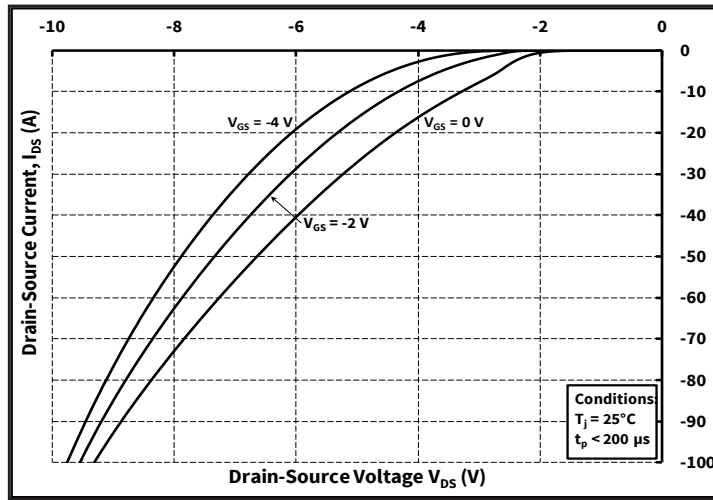


Figure 9. Body Diode Characteristic at 25 °C

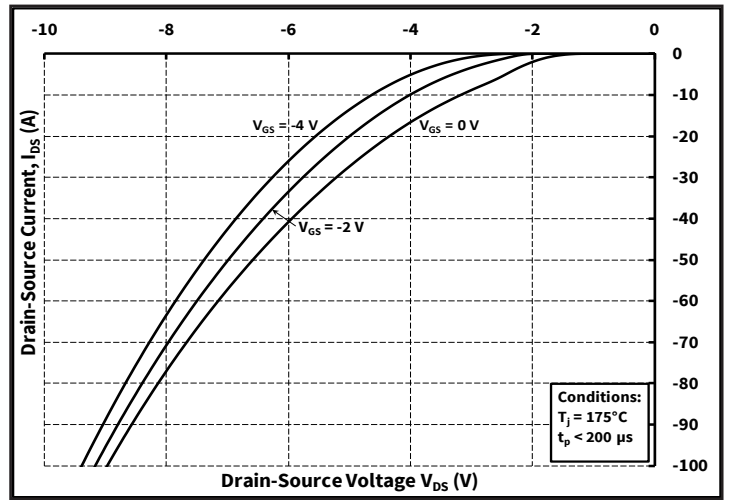


Figure 10. Body Diode Characteristic at 175 °C

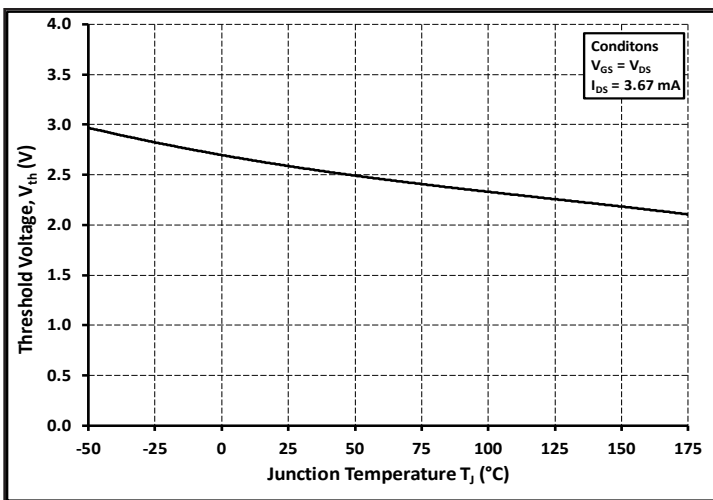


Figure 11. Threshold Voltage vs. Temperature

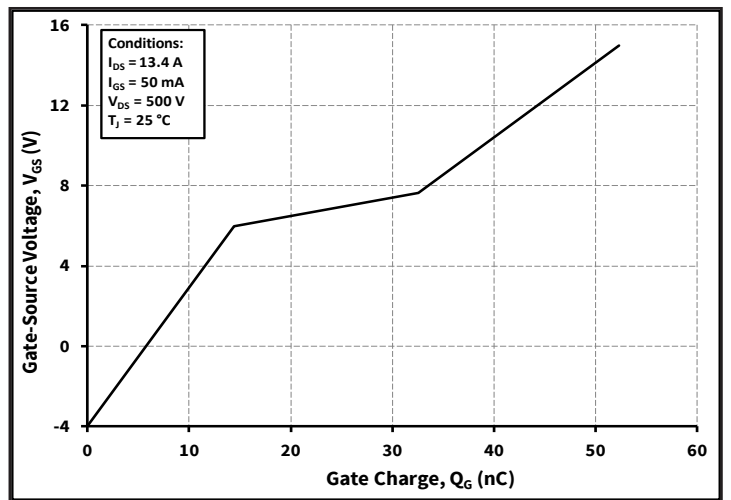


Figure 12. Gate Charge Characteristics



Typical Performance

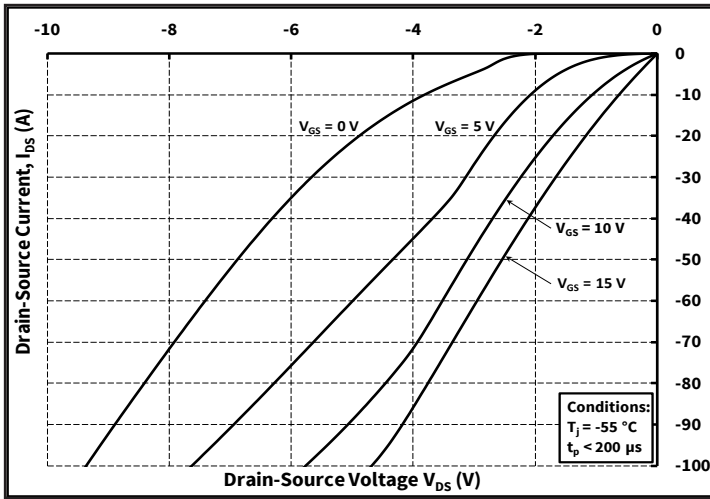


Figure 13. 3rd Quadrant Characteristic at -55 °C

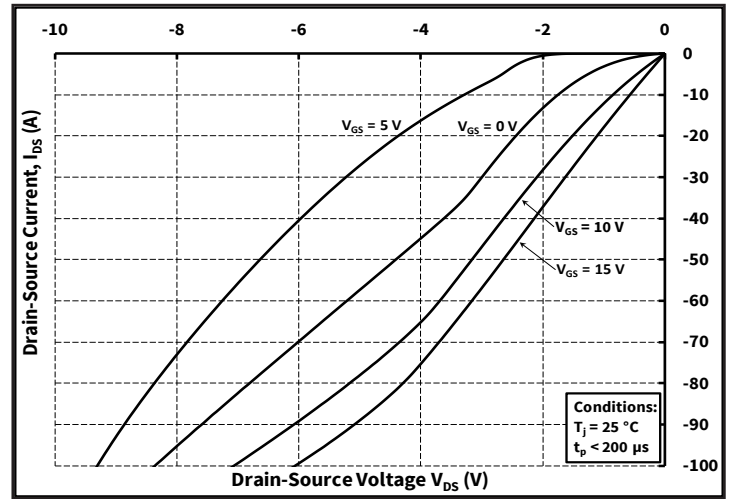


Figure 14. 3rd Quadrant Characteristic at 25 °C

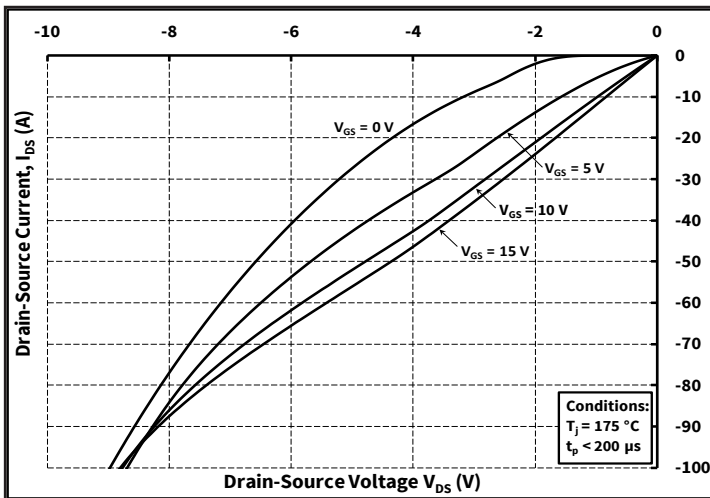


Figure 15. 3rd Quadrant Characteristic at 175 °C

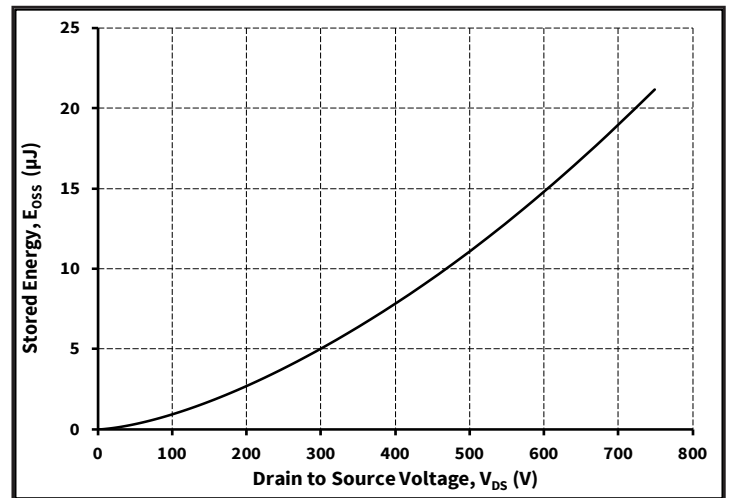


Figure 16. Output Capacitor Stored Energy

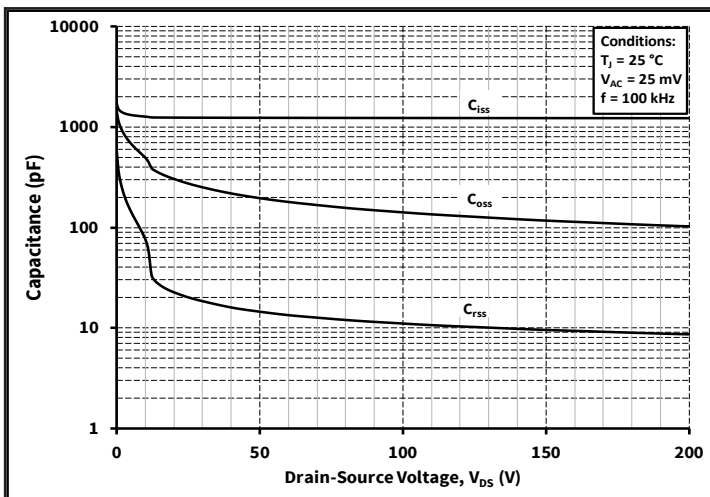


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200V)

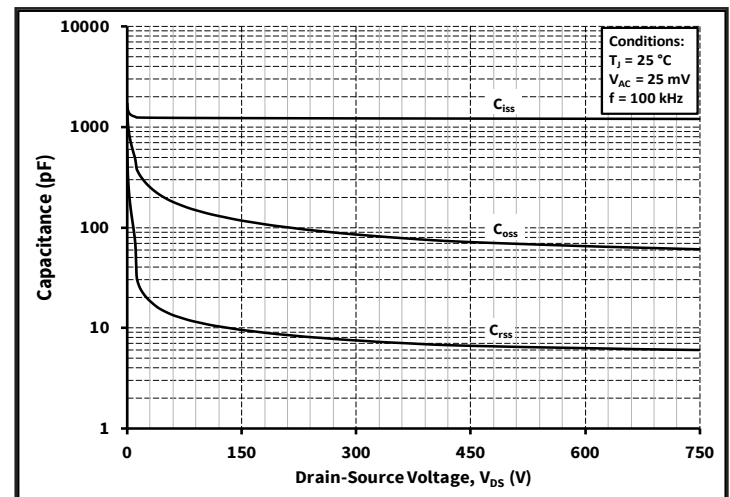


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 750V)



Typical Performance

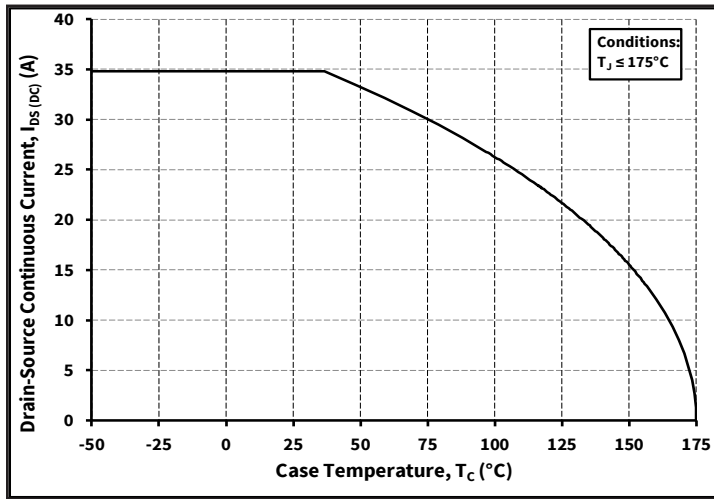


Figure 19. Continuous Drain Current Derating vs. Case Temperature

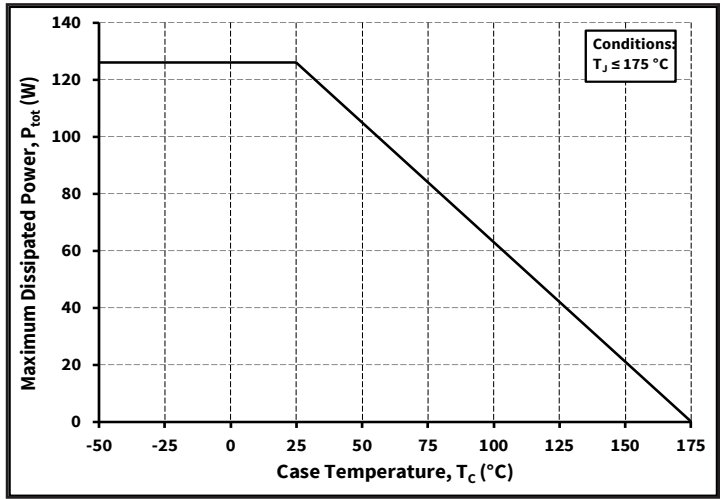


Figure 20. Maximum Power Dissipation Derating vs. Case Temperature

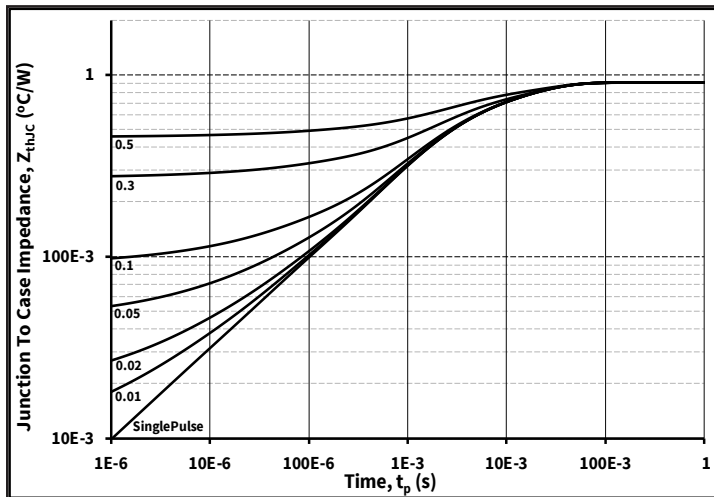


Figure 21. Transient Thermal Impedance (Junction - Case)

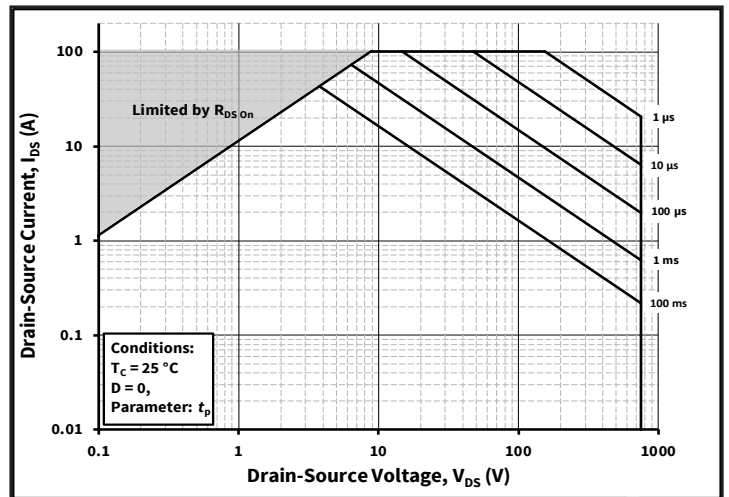


Figure 22. Safe Operating Area

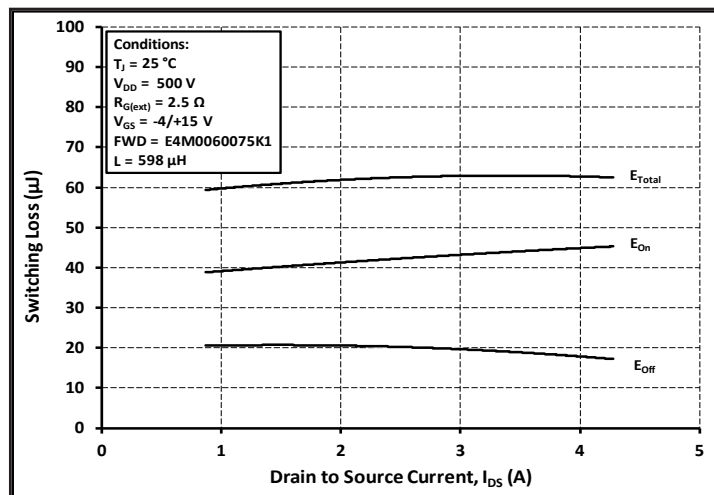


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 500V$ )

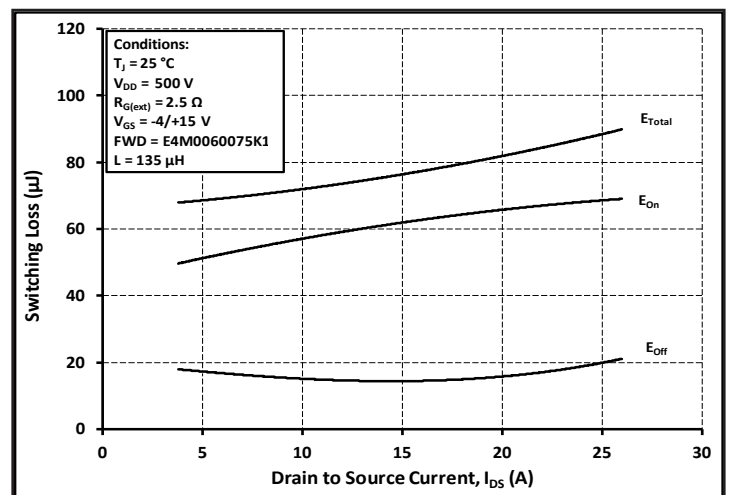


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 500V$ )



Typical Performance

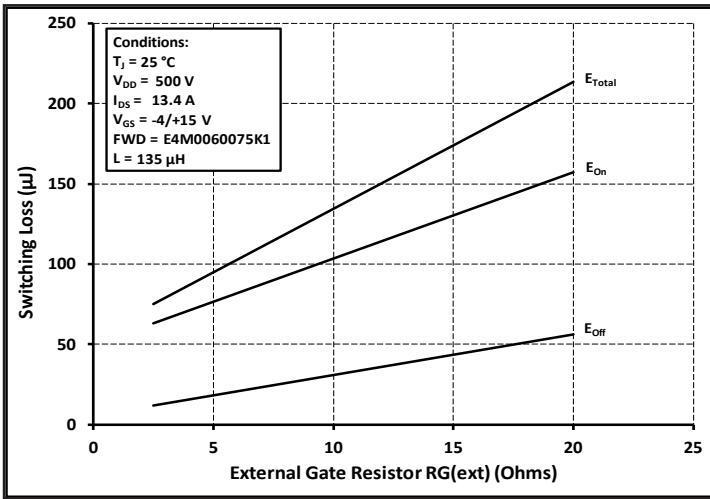


Figure 25. Clamped Inductive Switching Energy vs.  $R_{G(ext)}$

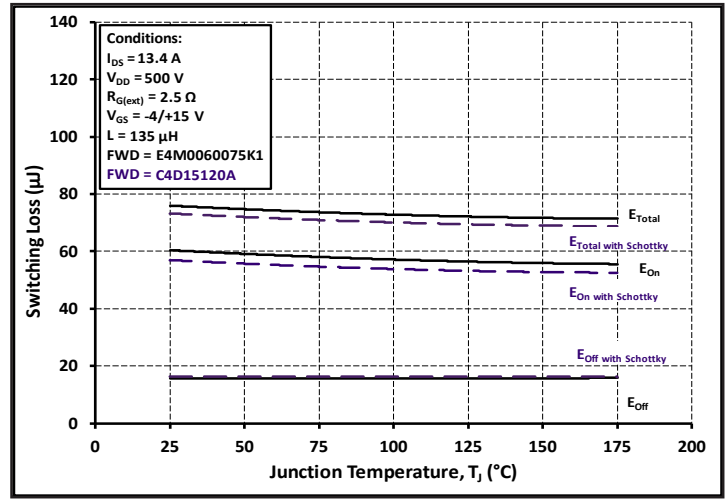


Figure 26. Clamped Inductive Switching Energy vs. Temperature

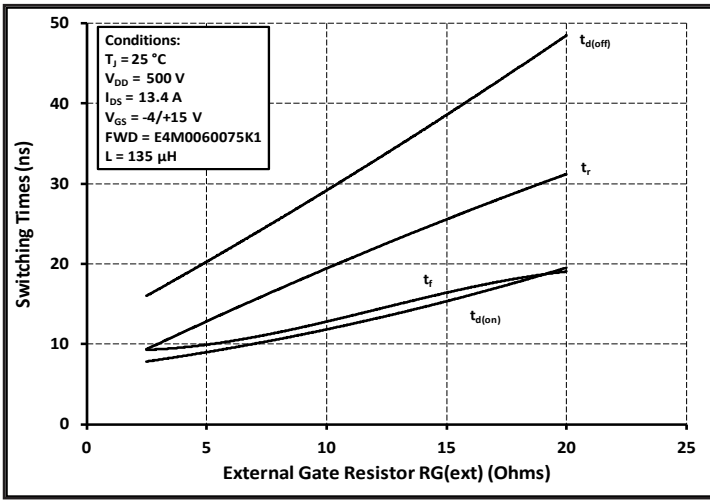


Figure 27. Switching Times vs.  $R_{G(ext)}$

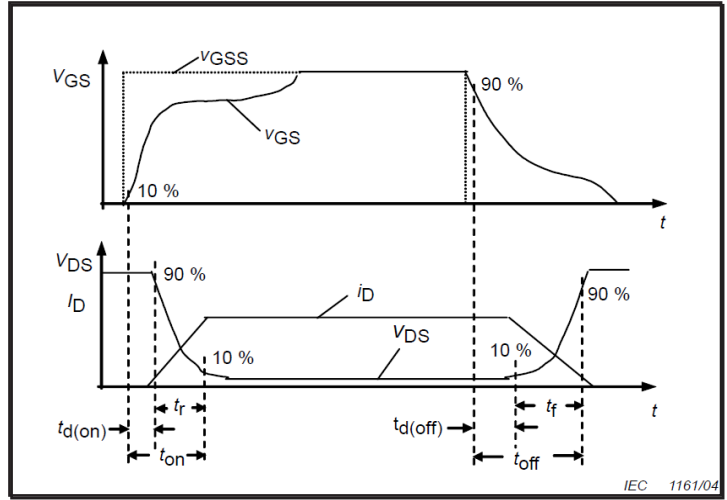


Figure 28. Switching Times Definition



## Test Circuit Schematic

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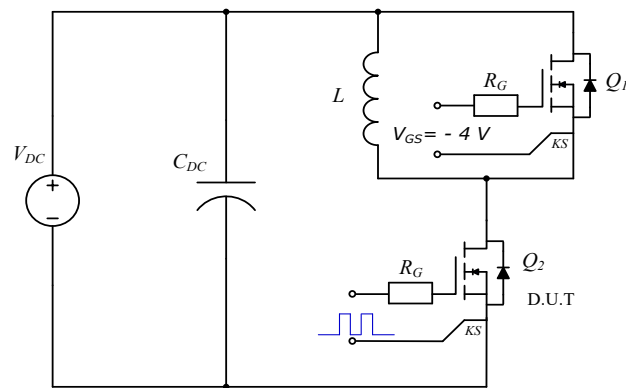
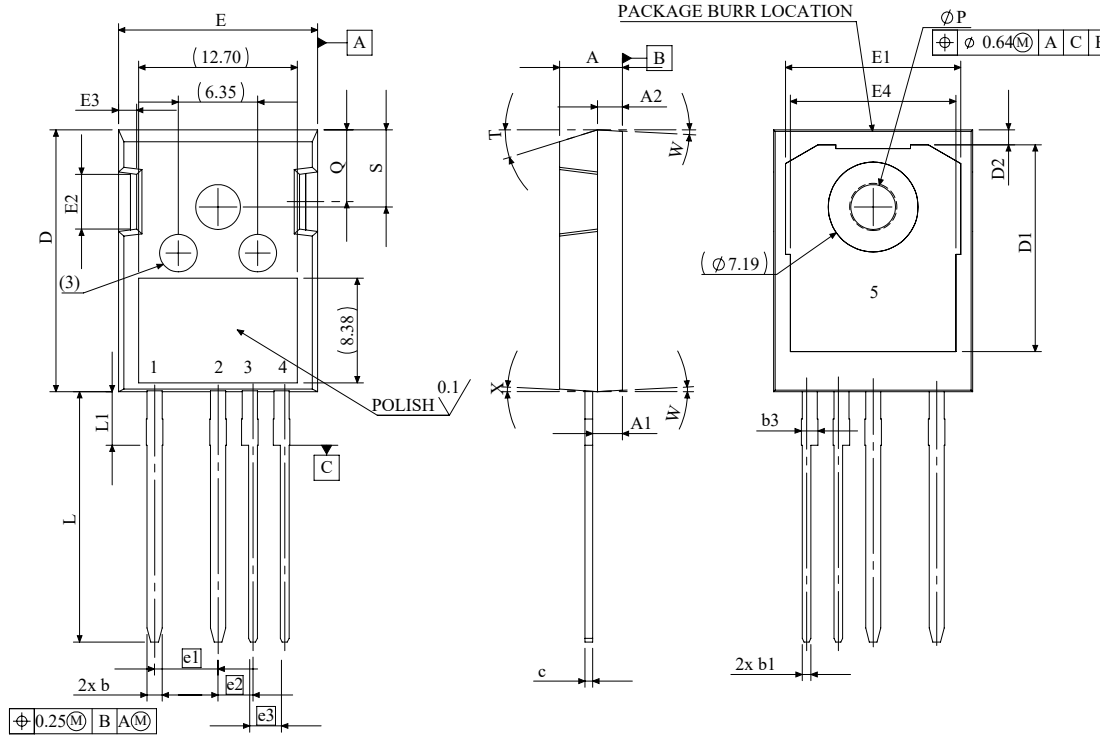


Figure 29. Clamped Inductive Switching  
Waveform Test Circuit

Package Dimensions



SYMBOL	MIN (mm)	MAX (mm)
A	4.83	5.21
A1	2.22	2.6
A2	1.91	2.16
b	1.10	1.30
b1	0.65	0.79
b3	1.34	1.44
c	0.55	0.68
D	20.76	21.14
D1	16.25	17.65
D2	0.92	1.42
E	15.75	16.13
E1	13.1	14.15
E2	3.68	5.10
E3	1.00	1.90
E4	12.38	13.43
e1	5.08 BSC	
e2	2.79 BSC	
e3	2.54 BSC	
L	19.72	20.32
L1	3.87	4.47
ØP	3.51	3.65
Q	5.49	6.00
S	6.04	6.30
T	17.5° REF.	
W	3.5° REF.	
X	4° REF.	

1	DRAIN
2	SOURCE
3	SOURCE
4	GATE
5	DRAIN

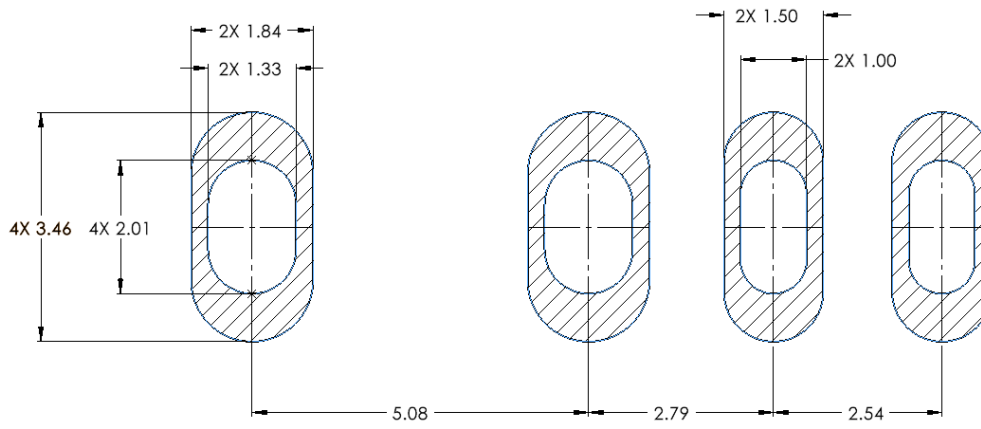
NOTE:

1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
4. BURR OR MOLD FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS



### Recommended Solder Pad Layout

All dimensions in mm





**Revision history**

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Document Version	Date of release	Description of changes
1.0	March-2024	Initial datasheet



## Notes & Disclaimer

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### **Contact info:**

4600 Silicon Drive  
Durham, NC 27703 USA  
Tel: +1.919.313.5300  
[www.wolfspeed.com/power](http://www.wolfspeed.com/power)